

THIN INTEGRATED CIRCUIT UNIT

ABSTRACT OF THE DISCLOSURE

A high density unit (130, 160) comprising a first integrated circuit package (30, 32) comprising a carrier (70) having first and second sides (92, 94), a silicon chip (50) attached by an adhesive layer (60) and solder bonding (80) electrically connecting the silicon chip (50) to the carrier (70) stackably and electrically connected to a second integrated circuit package (30, 32), is disclosed.

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